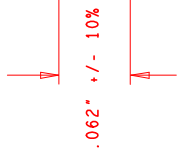
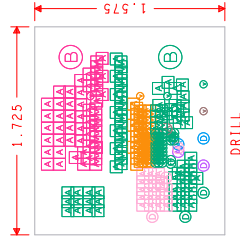


PHYSICAL BOARD DIMENSIONS & LAYER STRUCTURE




—	SILK TOP	<code>silk_t.art</code>
—	MASK TOP	<code>mask_t.art</code>
—	(TOP) COMPONENT	<code>layer1.art</code>
—	LAYER 2	<code>layer2.art</code>
—	LAYER 3	<code>layer3.art</code>
—	(BOTTOM) SOLDER	<code>layer4.art</code>
—	MASK BOTTOM	<code>maskb.art</code>
—	SILK BOTTOM	<code>silkb.art</code>



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
Ⓐ	10.0	PLATED	5
Ⓑ	11.0	PLATED	62
Ⓐ	12.0	PLATED	182
Ⓑ	40.0	PLATED	5
Ⓑ	46.0	PLATED	5
Ⓔ	215.0	PLATED	2

NOTES:

1. THIS BOARD IS RoHS COMPLIANT.
2. PRINTED WIRING BOARD DESIGN AND ACCEPTANCE CRITERIA SHALL BE IAW WITH THE REQUIREMENTS OF IPC-D-275 AND IPC-A-600.
3. MATERIAL: FR4 (RoHS COMPLIANT), 2 OZ COPPER LAYERS 1 & 4, 1 OZ. LAYERS 2 & 3..
4. APPLY SOLDER MASK, BOTH SIDES OVER BARE COPPER IAW IPC-SM-840. CLASS 2 (LPI) (BLUE MASK).
5. ALL PATTERNS ARE VIEWED FROM THE PRIMARY SIDE LOOKING THROUGH THE BOARD.
6. UNLESS OTHERWISE SPECIFIED ALL HOLE DIAMETERS ARE AFTER PLATING.
7. APPLY SILKSCREEN USING WHITE NON-CONDUCTIVE EPOXY BASED INK.
8. PWB MUST BE 100% ELECTRICALLY TESTED FOR SHORTS AND CONTINUITY. USE NETLIST PROVIDED ISL73033SLHEV1ZA_IPC356.IPC IAW IPC-D-356.
9. MARK DATE CODE AND MANUFACTURES IDENTIFICATION ON SOLDER SIDE PER IPC-6011 AND IPC-6012.
10. TOLERANCE ON ALL DRILL HOLES SHALL BE IAW IPC-D-2221 & 2222 UNLESS OTHERWISE SPECIFIED.
11. ALL 11 MIL VIAS ARE TO BE NON-CONDUCTIVE EPOXY FILLED AND CAPPED.

Drawn By: Tim Klemann	Date Drawn: 09/02/2020	Engineer: Kiran Bernard
Released By:	Date Released:	ISL73033SLH EVALUATION BOARD LAYOUT
Updated By:	Date Updated:	
	MASK#	REV. A
	HDWR ID	ISL73033SLHEV1Z
FILENAME:		SHEET
w/ISL73033SLH/ISL73033SLHEV1Z		1 of 1